PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
CHARLES L ARVIN	09/20/2010
VALERIE OBERSON	09/14/2010
SRINIVASA N REDDY	09/23/2010
KRYSTYNA W SEMKOW	09/14/2010
RICHARD A SHELLEMAN	09/22/2010
KAMALESH K SRIVASTAVA	09/15/2010

RECEIVING PARTY DATA

Name:	INTERNATIONAL BUSINESS MACHINES CORPORATION
Street Address:	NEW ORCHARD ROAD
City:	ARMONK
State/Country:	NEW YORK
Postal Code:	10504

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12894231

CH $40.00 12894231

CORRESPONDENCE DATA

Fax Number: (845)892-6363
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ATTORNEY DOCKET NUMBER:	FIS920100065US1

NAME OF SUBMITTER:	JOSEPH PETROKAITIS

Total Attachments: 12
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ASSIGNMENT

Whereas, the undersigned Inventor(s) has/have made certain inventions, improvements, and discoveries (herein referred to as the "Invention") in:

Title of the Invention: **CREATION OF LEAD-FREE SOLDER JOINT WITH INTERMETALLICS**

and further identified by the IBM Docket Number provided above in the header of this Assignment, for which an application for a United States Patent was executed concurrently herewith or was filed having:

Serial Number: ______________________ (insert series code and serial number here if/when available)

Whereas, International Business Machines Corporation, a corporation of New York having a place of business at Armonk, New York (herein referred to as "IBM"), desires to acquire, and each undersigned Inventor desires to grant to IBM, the entire worldwide right, title, and interest in and to the Invention and in and to any and all patent applications and patents directed thereto;

Now, therefore, for good and valuable consideration, the receipt and sufficiency thereof being hereby acknowledged, each undersigned Inventor ("ASSIGNOR") hereby sells, assigns, and otherwise transfers to IBM (the "ASSIGNEE"), its successors, legal representatives, and assigns, the entire worldwide right, title, and interest in and to the Invention, the above-identified United States patent application, and any and all other patent applications and patents for the Invention which may be applied for or granted therefor in the United States and in all foreign countries and jurisdictions, including all divisions, continuations, reissues, reexaminations, renewals, extensions, counterparts, substitutes, and extensions thereof, and all rights of priority resulting from the filing of such applications and granting of such patents. In addition, each undersigned Inventor hereby authorizes and requests the Director of the United States Patent and Trademark Office to issue any United States Patent, and foreign patent authorities to issue any foreign patent, granted for the Invention, to IBM, its successors, legal representatives, and assigns, the entire worldwide right, title, and interest in and to the same to be held and enjoyed by IBM, its successors, legal representatives, and assigns to the full end of the terms for which any and all such patents may be granted, as fully and entirely as would have been held and enjoyed by the undersigned had this Assignment not been made; and each undersigned Inventor agrees to execute any and all documents and instruments and perform all lawful acts reasonably related to recording this Assignment or perfecting title to the Invention and all related patents and applications, in IBM, its successors, legal representatives, and assigns, whenever requested by IBM, its successors, legal representatives, or assigns.

Each undersigned Inventor acknowledges their prior and ongoing obligations to sell, assign, and transfer the rights under this Assignment to IBM and is unaware of any reason why they may not have the full and unencumbered right to sell, assign, and transfer the rights hereby sold, assigned, and transferred, and has not executed, and will not execute, any document or instrument in conflict herewith. Each undersigned Inventor also hereby grants IBM, its successors, legal representatives, and assigns, the right to insert in this Assignment any further identification (including, but not limited to, patent application Serial Number) which may be necessary or desirable for recordation of this Assignment. This Assignment is governed by the substantive laws of the State of New York, and any disputes will be resolved in a New York state court or federal court sited in New York.

[Inventor Signature Page(s) Follows]

Executed by Inventor 1

Signature: ______________________ Date: 9-20-2010

Charles L. Arvin

Executed by Inventor 2

Signature: ______________________ Date: ______________

Valerie Oberson

Executed by Inventor 3

Signature: Srinivasa N. Reddy Date: Sept 23, 2010

Srinivasa N. Reddy

Executed by Inventor 4

Signature: ______________________ Date: ______________

Krystyna W. Semkow

Executed by Inventor 5

Signature: ______________________ Date: 9/22/10

Richard A. Shelleman

Executed by Inventor 6

Signature: ______________________________ Date: ______________
Kamalesh K. Srivastava

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[Inventor Signature Page(s) Follows]

1Executed by Inventor 1

Signature: ____________________ Date: ____________
Charles L. Arvin

1Executed by Inventor 2

Signature: ____________________ Date: 2010-09-14
Valerie Oberson

1Executed by Inventor 3

Signature: ____________________ Date: ____________
Srinivasa N. Reddy

1Executed by Inventor 4

Signature: ____________________ Date: ____________
Krystyna W. Semkow

1Executed by Inventor 5

Signature: ____________________ Date: ____________
Richard A. Shelleman

1Executed by Inventor 6

Signature: ________________________________ Date: ________________

Kamalesh K. Srivastava

IBM DOCKET NUMBER: **FIS920100065US1**

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Signature: ______________________ Date: ____________
Srinivasa N. Reddy

Executed by Inventor 4

Signature: Krystyna W. Semkow Date: 09/14/2010
Krystyna W. Semkow

Executed by Inventor 5

Signature: ______________________ Date: ____________
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